

Requested Patent: JP560623S1
Title: SEMICONDUCTOR DEVICE FOR MEMORY
Abstracted Patent: JP560623S1
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Applicant(s): HITACHI LTD
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Equivalents:

ABSTRACT:

PURPOSE: To increase the memory capacity along with a compacter size by bonding a plurality of a semiconductor pellets for memory in parallel with a lead frame employing a tape carrier.

CONSTITUTION: Projected electrodes 12 and 13 are formed on semiconductor pellets 10 and 11. Copper foils 14 and 15 provided on a tape carrier are fastened on electrodes 12 and 13 with the free end of the copper foils connected to the lead frame 16. The pellets 10 and 11 are solidly molded with a resin as a single package. This molding can reduce a space between the upper and lower pellets thereby making the device compact.